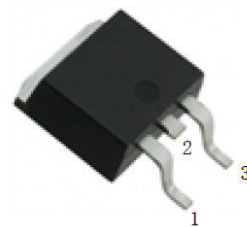
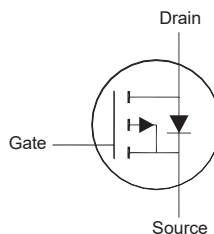


P-Channel Enhancement Mode MOSFET

Features

- Low On-Resistance
- Surface-mounted package
- Low Gate-Source Threshold Voltage
- Halogen and Antimony Free(HAF), RoHS compliant



1. Gate 2. Drain 3. Source
TO-252 Plastic Package

Key Parameters

Parameter	Value	Unit
$-BV_{DS}$	30	V
$R_{DS(ON)}$ Max	15 @ $-V_{GS} = 10$ V	$m\Omega$
	20 @ $-V_{GS} = 4.5$ V	
$-V_{GS(th)}$ typ	1.4	V
Q_g typ	43 @ $-V_{GS} = 10$ V	nC

Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	$-I_D$	49	A
		30	
Peak Drain Current, Pulsed ¹⁾	$-I_{DM}$	200	A
Single-Pulse Avalanche Current	$-I_{AS}$	30	A
Single-Pulse Avalanche Energy ²⁾	E_{AS}	45	mJ
Power Dissipation	P_D	44.9	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.7	$^\circ\text{C/W}$
Thermal Resistance from Junction to Ambient ³⁾	$R_{\theta JA}$	35	$^\circ\text{C/W}$

¹⁾ Pulse Test: Pulse Width $\leq 100 \mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.

²⁾ Limited by $T_{J(max)}$, starting $T_J = 25^\circ\text{C}$, $L = 0.1$ mH, $R_g = 25 \Omega$, $-I_{AS} = 30$ A, $V_{GS} = 10$ V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $-I_D = 250\ \mu\text{A}$	$-BV_{DS}$	30	-	-	V
Drain-Source Leakage Current at $-V_{DS} = 30\ \text{V}$	$-I_{DSS}$	-	-	1	μA
Gate Leakage Current at $V_{GS} = \pm 20\ \text{V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $-I_D = 250\ \mu\text{A}$	$-V_{GS(th)}$	1.0	-	2.5	V
Drain-Source On-State Resistance at $-V_{GS} = 10\ \text{V}$, $-I_D = 15\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$, $-I_D = 10\ \text{A}$	$R_{DS(on)}$	- -	12 -	15 20	$\text{m}\Omega$
DYNAMIC PARAMETERS					
Forward Transconductance at $-V_{DS} = 5\ \text{V}$, $-I_D = 10\ \text{A}$	g_{FS}	-	25.3	-	S
Gate Resistance at $V_{GS} = 0\ \text{V}$, $V_{DS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	R_g	-	4.2	-	Ω
Input Capacitance at $-V_{DS} = 15\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{iss}	-	2363	-	pF
Output Capacitance at $-V_{DS} = 15\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{oss}	-	244	-	pF
Reverse Transfer Capacitance at $-V_{DS} = 15\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{rss}	-	184	-	pF
Total Gate Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$	Q_g	- -	43 21	- -	nC
Gate-Source Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$	Q_{gs}	-	8	-	nC
Gate-Drain Charge at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$	Q_{gd}	-	8	-	nC
Turn-On Delay Time at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$, $R_G = 3.3\ \Omega$	$t_{d(on)}$	-	13	-	ns
Turn-On Rise Time at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$, $R_G = 3.3\ \Omega$	t_r	-	44	-	ns
Turn-Off Delay Time at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$, $R_G = 3.3\ \Omega$	$t_{d(off)}$	-	26	-	ns
Turn-Off Fall Time at $-V_{GS} = 10\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $-I_D = 15\ \text{A}$, $R_G = 3.3\ \Omega$	t_f	-	7	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $-I_S = 1\ \text{A}$, $V_{GS} = 0\ \text{V}$	$-V_{SD}$	-	-	1.2	V
Body-Diode Continuous Current	$-I_S$	-	-	49	A
Pulsed Body-Diode Continuous Current	$-I_{SM}$	-	-	200	A
Body Diode Reverse Recovery Time at $-I_S = 15\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	t_{rr}	-	14	-	ns
Body Diode Reverse Recovery Charge at $-I_S = 15\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	Q_{rr}	-	7	-	nC

Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

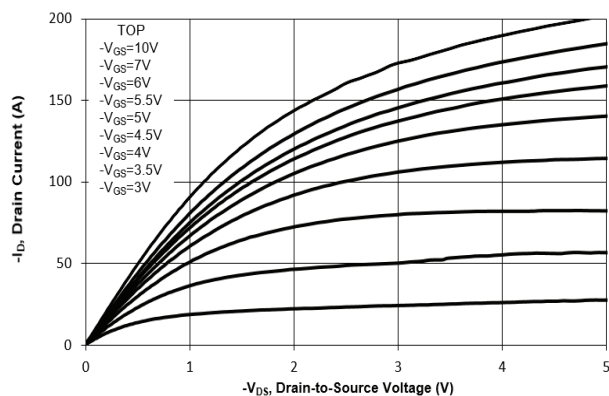


Fig. 2 Typical Transfer Characteristics

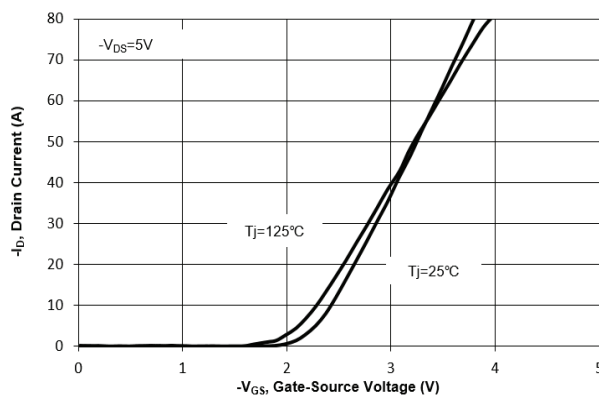


Fig. 3 on-Resistance vs. Drain Current

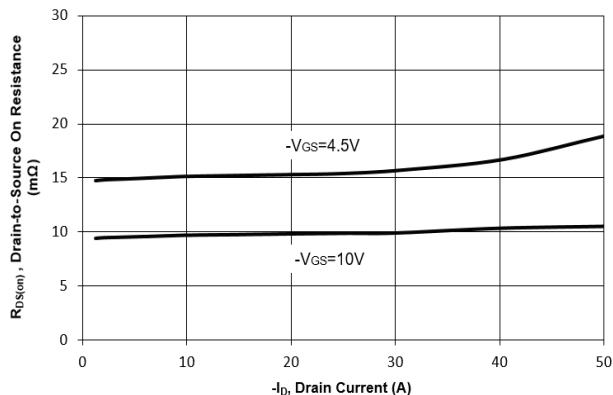


Fig. 4 on-Resistance vs. Gate to Source Voltage

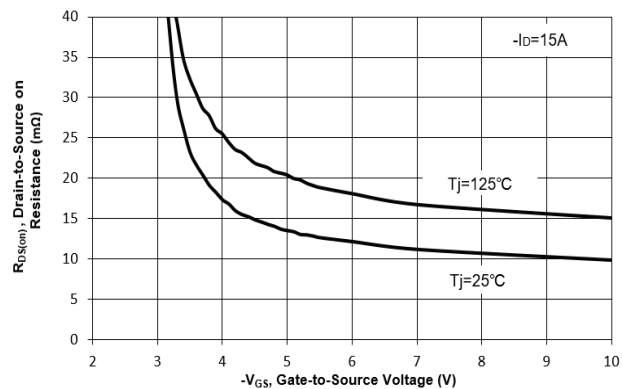


Fig. 5 on-Resistance vs. TJ

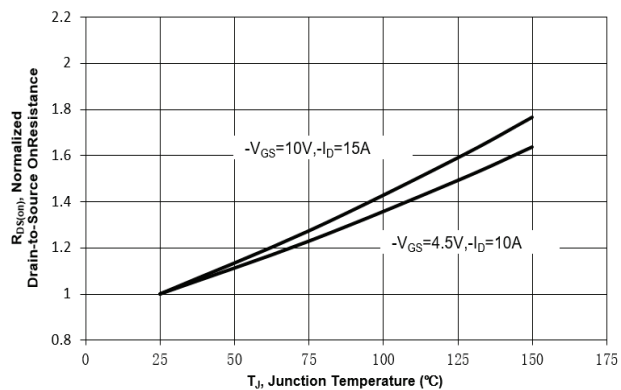
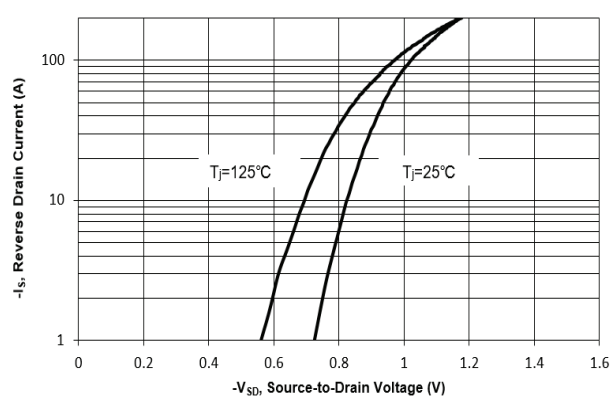


Fig. 6 Typical Body-Diode Forward Characteristics



Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

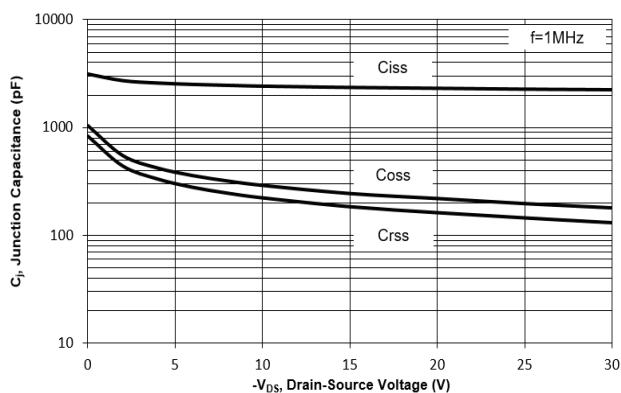


Fig. 8 Drain-Source Leakage Current vs. T_J

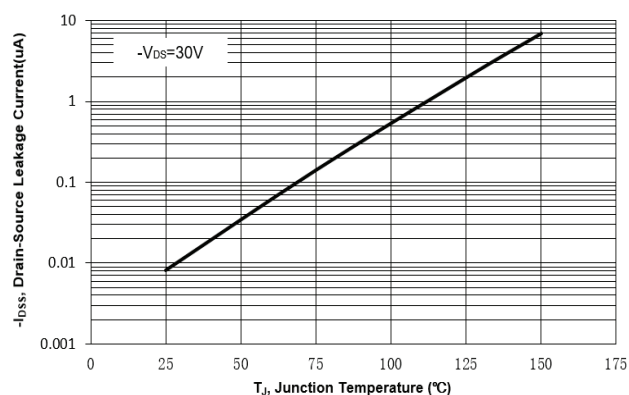


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

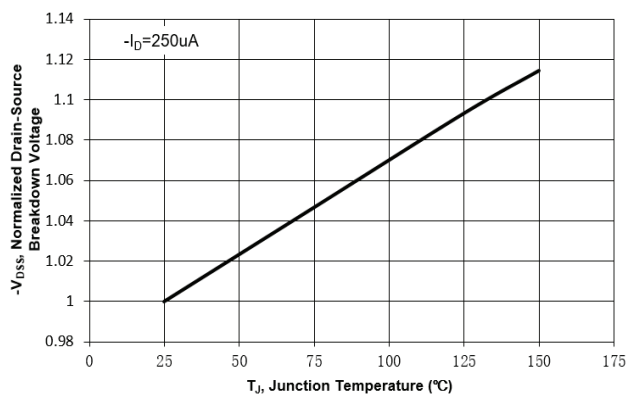


Fig. 10 Gate Threshold Variation vs. T_J

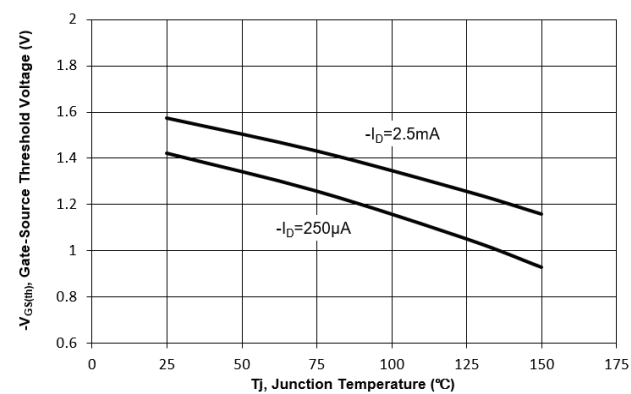


Fig. 11 Gate Charge

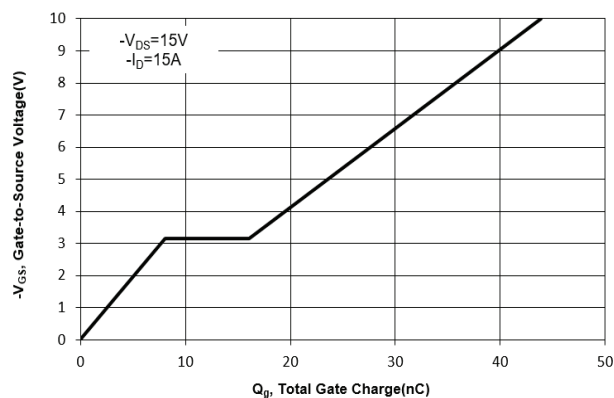
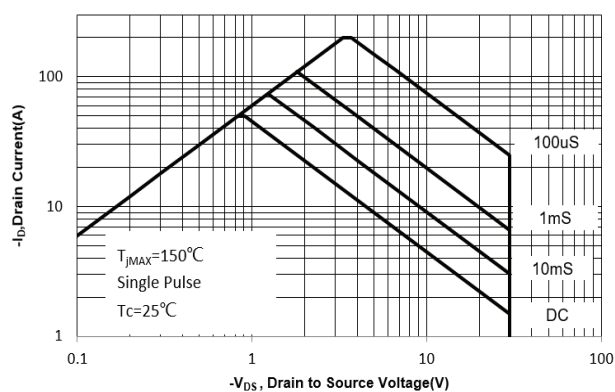


Fig. 12 Safe Operation Area



Electrical Characteristics Curves

Fig. 13 Normalized Maximum Transient Thermal Impedance($Z_{\theta JC}$)

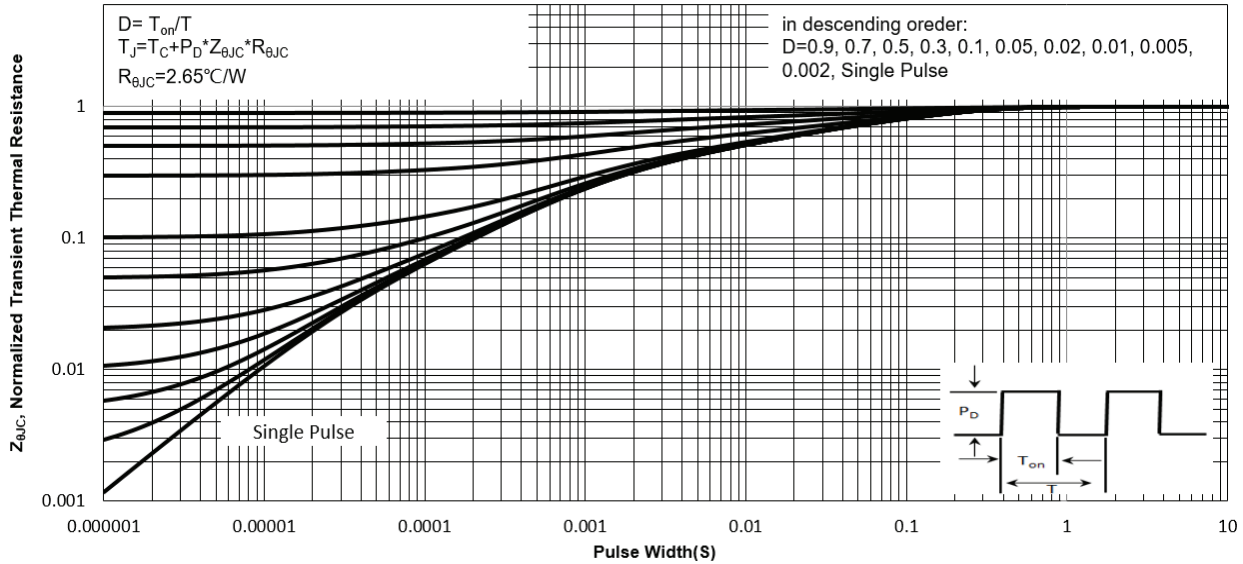
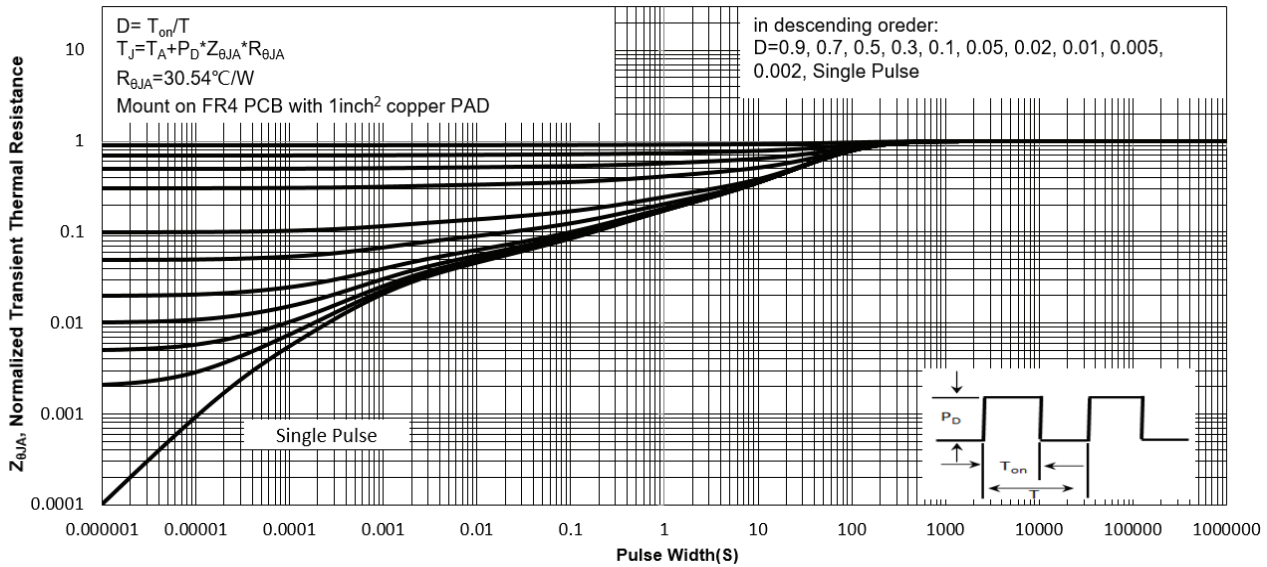
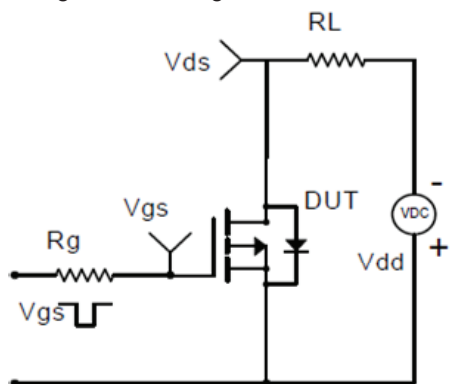
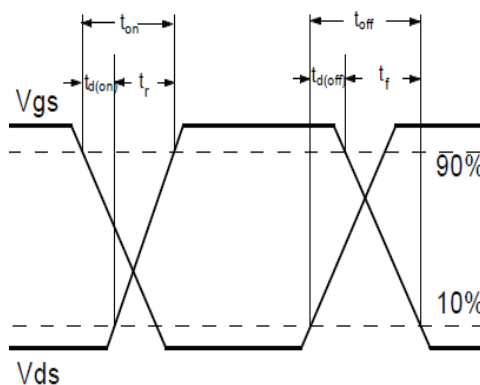
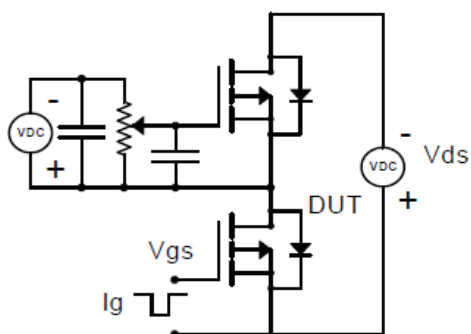
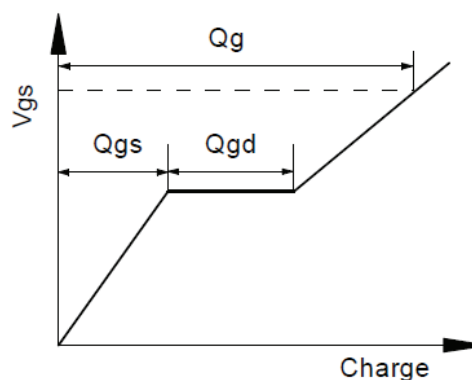
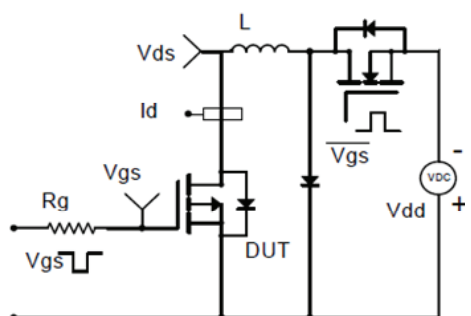
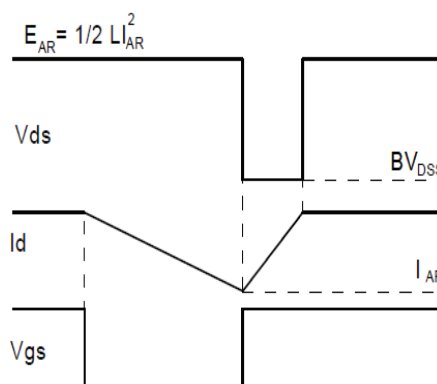


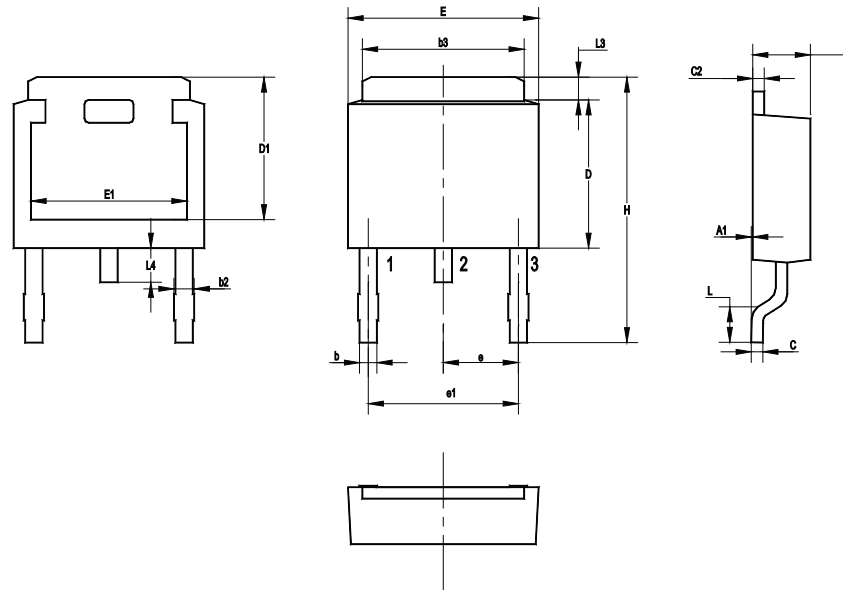
Fig. 14 Normalized Maximum Transient Thermal Impedance($Z_{\theta JA}$)



Test Circuits
Fig.1-1 Switching times test circuit

Fig.1-2 Switching Waveform

Fig.2-1 Gate charge test circuit

Fig.2-2 Gate charge waveform

Fig.3-1 Avalanche test circuit

Fig.3-2 Avalanche waveform


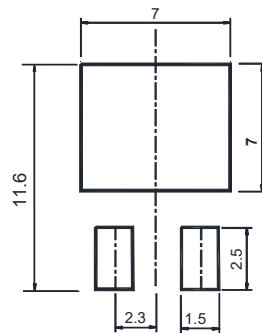
Package Outline (Dimensions in mm)

TO-252



UNIT	A	A1	b	b2	b3	C	C2	D	D1	E	E1	e	e1	H	L	L3	L4
mm	2.5	0.15	1.0	1.15	5.5	0.65	0.65	6.2	5.4	6.7	5.0	2.30	4.60	10.7	1.78	1.20	1.10
	2.1	0	0.5	0.65	4.9	0.4	0.4	5.6	5.0	6.1	4.6	TYP.	TYP.	9	1.40	0.85	0.51

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
TO-252	16	8 ± 0.1	0.315 ± 0.004	330	13	2,500

Marking information

" TR03P150LS " = Part No.

" ***** " = Date Code Marking

Font type: Arial



Disclaimer: Our company reserve the right to make modifications, enhancements, improvements, corrections or other changes to improve product design, functions and reliability, anytime without notice.